

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **05/28/2022**

Details for "AMS718AABXCQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
AMS718AABXCQ1		Level-3-250C-168 HR	Ext-Mfg	ABC 760	23x23x2.48	4240.5

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Lid							
Copper and Its Alloys	Copper	7440-50-8	2393.3195	98.45	984500	56.439068	564391
Nickel and Its Alloys	Nickel	7440-02-0	37.6805	1.55	15500	0.888579	8886
Sub-Total			2431	100	1000000	57.327647	573276
Lid Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	28.388193	70.000001	700000	0.669448	6694
Other Plastics and Rubber	Silicone	218163-11-2	12.166368	29.999999	300000	0.286906	2869
Sub-Total			40.554561	100	1000000	0.956354	9564
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	105.068757	100	1000000	2.477723	24777
Sub-Total			105.068757	100	1000000	2.477723	24777
Solder Ball							
Copper and Its Alloys	Copper	7440-50-8	1.956782	0.5	5000	0.046145	461
Other Nonferrous Metals and Alloys	Tin	7440-31-5	377.658887	96.5	965000	8.905922	89059
Precious Metals	Silver	7440-22-4	11.740691	3	30000	0.276868	2769
Sub-Total			391.35636	100	1000000	9.228934	92289
Solder Bump							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	7.512883	97.700002	977000	0.177168	1772
Precious Metals	Silver	7440-22-4	0.176864	2.299998	23000	0.004171	42
Sub-Total			7.689747	100	1000000	0.181339	1813
Substrate							
Copper and Its Alloys	Copper	7440-50-8	356.454	28.7	287000	8.40587	84059
Other Inorganic Materials	Silica	7631-86-9	18.2574	1.47	14700	0.430545	4305
Other Nonferrous Metals and Alloys	Tin	7440-31-5	13.041	1.05	10500	0.307532	3075
Precious Metals	Silver	7440-22-4	0.3726	0.03	300	0.008787	88
Thermoplastics	Epoxy	85954-11-6	853.875	68.75	687500	20.136012	201360
Sub-Total			1242	100	1000000	29.288744	292887
Underfill							
Other Inorganic Materials	Fused Silica	60676-86-0	18.293955	80.000003	800000	0.431407	4314
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.228674	0.999998	10000	0.005393	54
Other Plastics and Rubber	Carbon Black	1333-86-4	0.114337	0.499999	5000	0.002696	27
Thermoplastics	Epoxy	85954-11-6	4.230477	18.5	185000	0.099763	998
Sub-Total			22.867443	100	1000000	0.539258	5393
Total			4240.536868			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 05/28/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.